PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HAENG LEEM JEON	08/28/2007

RECEIVING PARTY DATA

Name:	DONGBU HITEK CO., LTD.
Street Address:	891-10 DAECHI-DONG, GANGNAM-GU
City:	SEOUL
State/Country:	REPUBLIC OF KOREA
Postal Code:	135-280

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11848640

OP $40.00 11848640

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SUN-DH-363
NAME OF SUBMITTER:	JEFF LLOYD

Total Attachments: 2
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Docket No. SUN-DH-363

ASSIGNMENT

WHEREAS, I, the undersigned, residing at the indicated address given below, respectively, have invented certain new and useful improvements in **SEMICONDUCTOR AND METHOD FOR MANUFACTURING THE SAME**, for which an application for United States Letters Patent was filed August 31, 2007, as Serial No. 11/848,640.

WHEREAS, **DONGBU HITEK CO., LTD.**, a corporation of the country of the **Republic of Korea**, having a place of business at **891-10 Daechi-dong, Gangnam-gu, Seoul 135-280, Republic of Korea** is desirous of acquiring the entire right, title, and interest in and to said invention and in and to any Letters Patent which may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in view of valuable consideration, receipt of which is hereby acknowledged, I, the undersigned, have sold, assigned, and transferred, and by these presents do sell, assign, and transfer, unto said **DONGBU HITEK CO., LTD.**, its successors and assigns, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title, and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, and extensions thereof.

I hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to **DONGBU HITEK CO., LTD.**, as the assignee of the entire right, title, and interest in and to the same, for the sole use and behoof of said **DONGBU HITEK CO., LTD.**, its successors and assigns.

FURTHER, I agree that I will communicate to said **DONGBU HITEK CO., LTD.**, or its representatives, any facts known to me respecting said invention; testify in any legal proceedings; sign all lawful papers; execute all divisional, continuation, substitution, renewal, and reissue applications; execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said **DONGBU HITEK CO., LTD.**; make all rightful oaths; and generally do everything possible to aid the said **DONGBU HITEK CO., LTD.**, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

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IN TESTIMONY WHEREOF, I have hereunto set my hand this 28th day of Aug, 2007.

Signature:
JEON, Haeng Leem
902-101, Mokrycon Apt., 1053-3 Hogyc-dong,
Dongan-gu, Anyang-si, Gyeonggi-do, Korea

WITNESS: Y. K. Jung

Signature:

Printed Name: Yoon Kyung JUNG

Date: August 28, 2007

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